

# **Automotive (A2)**

# SPI

# **128K Bits EEPROM**

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#### 1. Features

- Serial Peripheral Interface (SPI) Compatible
  - Supports Mode 0 (0,0) and Mode 3 (1,1)
- Wide-voltage Operation
  - Vcc = 2.5V to 5.5V
- Low power CMOS
  - Standby current: ≤5 μA (5.5V)
  - Operating current: ≤5 mA (5.5V)
- Operating frequency: 20 MHz (5.5V)
- Memory organization: 128Kb (16,384 x 8)
- Byte and Page write (up to 64 bytes)
  - Partial page write allowed
- Block Write Protection

- Protect 1/4, 1/2, or Entire Array
- Additional Write lockable Page (Identification page)
- Self timed write cycle: 5 ms (max.)
- High-reliability
  - Endurance: 1 million cycles
  - Data retention: 100 years
- Compliant with automotive standard AEC-Q100 grade 2
- Packages (8-pin): SOIC, TSSOP AND UDFN
- Lead-free, RoHS, Halogen free, Green

### 2. General Description

The GT25C128A is a standard electrically erasable programmable read only memory (EEPROM) product that utilizes standard Serial Peripheral Interface (SPI) for communications. The GT25C128A contains a memory array of 128K bits (16,384x 8), which is organized in 64 bytes per page.

This EEPROM operates in a wide voltage range from 2.5V to 5.5V, which fits most application. The device provides low-power operations and low standby current. The product is offered in Lead-free, RoHS, halogen free or Green package. The available package types are 8-pin SOIC, TSSOP AND UDFN.

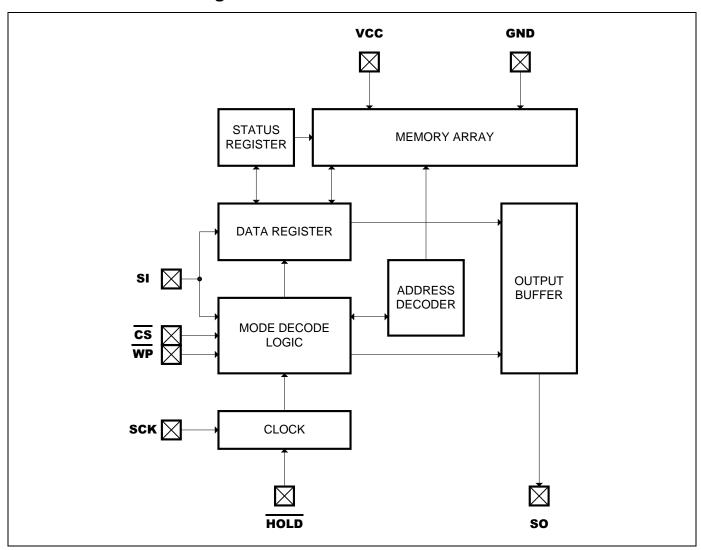
The functionalities of the GT25C128A are optimized for most applications, such as consumer electronics, wireless, telecommunication, industrial, medical, instrumentation, commercial and others, where low-power and low-voltage are vital. This product has a compatible SPI interface: Chip-Select ( $\overline{\text{CS}}$ ), Serial Data In (SI), Serial Data Out (SO) and Serial Clock (SCK) for high-speed communication. Furthermore, a Hold feature via  $\overline{\text{HOLD}}$  pin allows the device entering into a suspended state whenever necessary and resuming the communication without re-initializing the serial sequence. A Status Register facilitates a flexible write protection mechanism and device

status monitoring. The GT25C128A also offers an additional page, named the Identification Page (64 bytes) which can be written and (later) permanently locked in Read-only mode. This Identification Page offers flexibility in the application board production line, as the Identification Page can be used to store unique identification parameters and/or parameters specific to the production line.

In order to refrain the state machine from entering into a wrong state during power-up sequence or a power toggle off-on condition, a power on reset circuit is implemented. During power-up, the device does not respond to any instructions until the supply voltage (Vcc) has reached an acceptable stable level above the reset threshold voltage. Once Vcc passes the power on reset threshold, the device is reset and enters into Standby mode. This should also avoid any inadvertent Write operations during power-up stage. During power-down process, the device will enter into standby mode, once V<sub>CC</sub> drops below the power on reset threshold voltage. In addition, the device will be in standby mode after receiving the Stop command, provided that no internal write operation is in progress. Nevertheless, it is illegal to send a command unless the Vcc is within its operating level.



### 3. Functional Block Diagram



### **Serial Interface Description**

**Master:** The device that provides a clock signal.

Slave: GT25C128A.

Transmitter/Receiver: The GT25C128A has both data input (SI) and data output (SO).

MSB (Most Significant Bit) is the first bit being transmitted or received.

**Op-Code:** Operational instruction code typically sent to the GT25C128A is the first byte of information

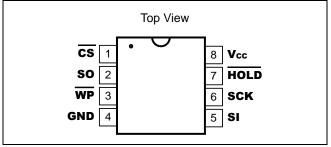
transmitted after  $\overline{\text{CS}}$  is Low. If the Op-Code is a valid instruction as listed in Table 5.3, then it will be

decoded appropriately. It is prohibited to send an invalid Op-Code.

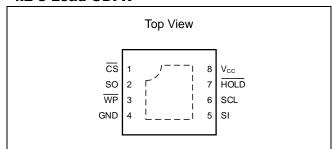


### 4. Pin Configuration

#### 4.1 8-Pin SOIC, TSSOP



#### 4.2 8-Lead UDFN



#### 4.3 Pin Definition

Pin No.	Pin Name	I/O	Definition
1	CS 	I	Chip Select
2	SO	0	Serial Data Output
3	WP	I	Write Protect Input
4	GND	-	Ground
5	SI	I	Serial Data Input
6	SCK	I	Serial Clock
7	HOLD	I	Hold function
8	Vcc	-	Supply Voltage

#### **4.4 Pin Descriptions**

#### Chip Select (CS)

The  $\overline{\text{CS}}$  pin is used to enable or disable the device. Upon power-up,  $\overline{\text{CS}}$  must follow the supply voltage. When the device is ready for instruction input, this signal requires a High-to-Low transition. Once  $\overline{\text{CS}}$  is stable at Low, the device is enabled. Then the master and slave can communicate among each other through SCK, SI, and SO pins. Upon completion of transmission,  $\overline{\text{CS}}$  must be driven to High in order to stop the operation or start the internal write operation. And the device will enter into standby mode, unless an internal write operation is in progress. During this mode, SO becomes high impedance.

#### Serial Clock (SCK)

Under the SPI modes (0, 0) and (1, 1), this clock signal provides synchronization between the master and GT25C128A. Typically, Op-Codes, addresses and data are latched from SI at the rising edge of SCK, while data from SO are clocked out at the falling edge of SCK.

#### Serial Data Input (SI)

Data Input pin.

#### **Serial Data Output (SO)**

Data output pin.

#### Write Protect ( $\overline{WP}$ )

This active Low input signal is utilized to initiate Hardware Write Protection mode. This mode prevents the Block Protection bits and the WPEN bit in the Status Register from being modified. To activate the Hardware Write Protection,  $\overline{\text{WP}}$  must be Low simultaneously when WPEN is set to 1.

#### Hold (HOLD)

This feature is used to suspend the device in the middle of a serial sequence and temporarily ignore further communication on the bus (SI, SO, SCK). The HOLD signal transitions must occur only when SCK is Low and be held stable during SCK transitions. Connecting HOLD to High disables this feature. Figure. 5-8 shows Hold timing.



Note: HOLD cannot be powered on earlier than Vcc, and

the amplitude of HOLD cannot be greater than Vcc.

#### 5. Device Operation

#### **5.1 Status Register**

The Status Register accessible by the user consists of 8-bits data for write protection control and write status. It

becomes Read-Only under any of the following conditions: Hardware Write Protection is enabled or WEN is set to 0. If neither is true, it can be modified by a valid instruction.

#### **Table 5.1: Status Register**

Bit	Symbol	Name	Description
			When $\overline{RDY} = 0$ , device is ready for an instruction.
0	RDY	Ready	When $\overline{RDY} = 1$ , device is busy.
			As busy, device only accepts Read Status Register command.
			This represents the write protection status of the device.
			When WEN = 0, Status Register and entire array cannot be modified, regardless
1	WEN	Write Enable	the setting of WPEN, WP pin or block protection.
			Write Enable command (WREN) can be used to set WEN to 1.
			Upon power-up stage, WEN is reset to 0.
2	BP0	Block Protect Bit	Despite of the status on WPEN, WP or WEN, BP0 and BP1 configure any
3	DD4	Disale Drestant Dit	combinations of the four blocks being protected (Table 5.2).
3	BP1	Block Protect Bit	They are non-volatile memory and programmed to 0 by factory.
4	Х	Don't Care	Values can be either 0 or 1, but are not retained. Mostly always 0, except during
5	Х	Don't Care	write operation.
6	Х	Don't Care	
			This bit can be utilized to enable Hardware Write Protection, together with
			WP pin. If enabled, Status Register becomes read-only. However, the memory
7	WDEN	Muita Duata et Eurahia	array is not protected by this mode. Hardware Write Protection requires the
7	7 WPEN Write Protect Enable		setting of $\overline{WP} = 0$ and WPEN = 1. Otherwise, it is disabled.
			WPEN cannot be altered from 1 to 0 if WP is already set to Low. (Table 5.4 for
			write protection)

#### Note:

- 1, During internal write cycles, bits 0 to bit 7 are temporarily 1's.
- 2, After performing the write operation, the Ready bit may appear at any position from bit 0 to bit 7 when it first changes from 1b to 0b. When reading this result, Master needs to read the register again to read the correct value.
- 3, The method of delaying reading the register by 5ms after the write operation is also recommended.

#### Table 5.2: Block Protection by BP0 and BP1

Lovel	Status Register Bits		Avvey Addresses Bretested	
Level	BP1	BP0	Array Addresses Protected	
0	0	0	None	
1 (1/4)	0	1	3000h-3FFFh	
2 (1/2)	1	0	2000h-3FFFh	





3 (All)	1	1	0000h-3FFFh	

#### 5.2 Op-Code Instructions

The operations of the GT25C128A are controlled by a set of instruction Op-Codes (Table 5.3) that are clocked-in serially via SI pin. To initiate an instruction, the chip select ( $\overline{CS}$ ) must be Low. Subsequently, each Low-to-High transition of the clock (SCK) will latch a stable level from SI. After the 8-bit Op-Code, it may continue to latch-in an address and/or data from SI accordingly, or to output data from SO. During

data output, data are latched out at the falling edge of SCK. All communications start with MSB first. Upon the transmission of the last bit but prior to any following Low-to-High transition on SCK,  $\overline{\text{CS}}$  must be brought to High in order to end the transaction and start the operation. The device will enter into Standby Mode after the operation is completed.

Table 5.3: Instruction Op-Codes[1,2,3]

Name	Op-Code	Operation	Address	Data (SI)	Data (SO)
WREN	0000 X110	Set Write Enable Latch	-	-	-
WRDI	0000 X100	Reset Write Enable Latch	-	-	-
RDSR	0000 X101	Read Status Register	-	-	D <sub>7</sub> -D <sub>0</sub> -
WRSR	0000 X001	Write Status Register	-	D <sub>7</sub> -D <sub>0</sub>	-
READ	0000 X011	Read Data from Array	A <sub>15</sub> -A <sub>0</sub>	-	D <sub>7</sub> -D <sub>0</sub> ,
WRITE	0000 X010	Write Data to Array	A <sub>15</sub> -A <sub>0</sub>	D <sub>7</sub> -D <sub>0</sub> ,	-
Read Identification Page	1000 X011 <sup>[4]</sup>	Read the page dedicated	A <sub>15</sub> -A <sub>0</sub>	D <sub>7</sub> -D <sub>0</sub> ,	-
		to identification			
Write Identification Page	1000 X010 <sup>[4]</sup>	Write the page dedicated	A <sub>15</sub> -A <sub>0</sub>	D <sub>7</sub> -D <sub>0</sub> ,	-
		to identification			
Read Lock Status	1000 X010 <sup>[5]</sup>	Reads the lock status of	A <sub>15</sub> -A <sub>0</sub>	D <sub>7</sub> -D <sub>0</sub> ,	-
		the Identification Page.			
Lock ID	1000 X010 <sup>[5]</sup>	Locks the Identification	A <sub>15</sub> -A <sub>0</sub>	D <sub>7</sub> -D <sub>0</sub> ,	-
		page in read-only mode.			

Notes: [1] X = Don't care bit. However, it is recommended to be "0".

#### 5.3 Write Enable

When Vcc is initially applied, the device powers up with both status register and entire array in a write-disabled state. Upon completion of Write Disable (WRDI), Write Status Register (WRSR) or Write Data to Array (WRITE), the device resets the WEN bit in the Status Register to 0. Prior to any data modification, a Write Enable (WREN) instruction is necessary to set WEN to 1 (Figure. 5-2).

#### **5.4 Write Disable**

The device can be completely protected from modification by resetting WEN to 0 through the Write Disable (WRDI) instruction (Figure. 5-3).

#### 5.5 Read Status Register

The Read Status (RDSR) instruction reviews the status of Write Protect Enable, Block Protection setting (Table 5.2), Write Enable state and RDY status. RDSR is the only

<sup>[2]</sup> Some address bits may be don't care (Table 5.5).

<sup>&</sup>lt;sup>[3]</sup> It is strongly recommended that an appropriate format of Op-Code must be entered. Otherwise, it may cause unexpected phenomenon to be occurred. Nevertheless, it is illegal to input invalid any Op-Code.

<sup>[4]</sup> Address bit A10 must be 0, all other address bits are Don't Care.

<sup>&</sup>lt;sup>[5]</sup> Address bit A10 must be 1, all other address bits are Don't Care.



instruction accepted when a write cycle is underway. It is recommended that the status of Write Enable and RDY be checked, especially prior to an attempted modification of data. These 8 bits information can be repeatedly output on SO after the initial Op-Code (Figure. 5-4).

#### 5.6 Write Status Register

The Write Status Register (WRSR) instruction allows the user to choose a Block Protection setting and set or reset the WPEN bit. The values of the other data bits incorporated into WRSR can be 0 or 1 and are not stored in the Status Register. WRSR will be ignored unless both following conditions are true: a) WEN = 1, due to a prior WREN instruction; and b) Hardware Write Protection is not enabled (Table 5.4). Except for  $\overline{\text{RDY}}$  status, the values in the Status Register remain unchanged until the moment when the write cycle is completed and the register is updated. Note that WPEN can be changed from 1 to 0 only if  $\overline{\text{WP}}$  is already set High. Once completed, WEN is reset for complete chip write protection (Fig. 5-5).

#### 5.7 Read Data

This instruction includes an Op-Code and 16-bit address, then results the selected data to be shifted out from SO. Following the first data byte, additional sequential data can be output. If the data byte of the last address is initially output, then address will rollover to the first address in the array, and the output could loop indefinitely. At any time, a rising  $\overline{\text{CS}}$  signal ceases the operation (Figure. 5-6).

#### 5.8 Write Data

The WRITE instruction contains an Op-Code, a 16-bit address and the first data byte. Additional data bytes may be supplied sequentially after the first byte. Each WRITE instruction can affect up to 64 bytes of data in a page. Each page has a starting address XXXXXXXX XX000000 and an ending address XXXXXXXXX XX111111. After the last byte of data in a page is input, the address rolls over to the beginning of the same page. If more than 64 bytes of data is input during a single instruction, then only the last 64 bytes will be retained, but the initial data will be overwritten.

The contents of the array defined by Block Protection cannot be modified as long as that block configuration is selected. The contents of the array outside the Block

Protection can only be modified if Write Enable (WEN) is set to 1. Therefore, it may be necessary that a WREN instruction is initiated prior to WRITE. Once Write operation is completed, WEN is reset for complete chip write protection (Figure. 5-7). Besides, Hardware Write Protection has no affect on the memory array.

#### **5.9 Read Identification Page**

The Identification Page (64 bytes) is an additional page which can be written and (later) permanently locked in Read-only mode. Reading this page is achieved with the Read Identification Page instruction (see Table 5.3).

The Chip Select signal ( $\overline{\text{CS}}$ ) is first driven low, the bits of the instruction byte and address bytes are then shifted in, on Serial Data input (SI). Address bit A10 must be 0, address bits [A15:A11] and [A9:A6] are Don't Care, and the data byte pointed to by [A5:A0] is shifted out on Serial Data output (SO). If Chip Select ( $\overline{\text{CS}}$ ) continues to be driven low, the internal address register is automatically incremented, and the byte of data at the new address is shifted out.

The number of bytes to read in the ID page must not exceed the page boundary (e.g. when reading the ID page from location 24d, the number of bytes should be less than or equal to 40d, as the ID page boundary is 64 bytes). The read cycle is terminated by driving Chip Select ( $\overline{\text{CS}}$ ) high. The rising edge of the Chip Select ( $\overline{\text{CS}}$ ) signal can occur at any time during the cycle. The first byte addressed can be any byte within any page (Figure. 5-8).

The instruction is not accepted, and is not executed, if a write cycle is currently in progress.

#### **5.10 Write Identification Page**

The Identification Page (64 bytes) is an additional page which can be written and (later) permanently locked in Read-only mode. Writing this page is achieved with the Write Identification Page instruction (see Table 5.3), the Chip Select signal ( $\overline{\text{CS}}$ ) is first driven low. The bits of the instruction byte, address byte, and at least one data byte are then shifted in on Serial Data input (SI). Address bit A10 must be 0, address bits [A15:A11] and [A9:A6] are Don't Care, the [A5:A0] address bits define the byte address inside the identification page. The instruction sequence is shown in Figure 5-9.



#### **5.11 Read Lock Status**

The Read Lock Status instruction (see Table 5.3) allows to check if the Identification Page is locked (or not) in read-only mode. The Read Lock Status sequence is defined with the Chip Select ( $\overline{\text{CS}}$ ) first driven low. The bits of the instruction byte and address bytes are then shifted in on Serial Data input (SI). Address bit A10 must be 1, all other address bits are Don't Care. The Lock bit is the LSB (least significant bit) of the byte read on Serial Data output (SO). It is at '1' when the lock is active and at '0' when the lock is not active. If Chip Select ( $\overline{\text{CS}}$ ) continues to be driven low, the same data byte is shifted out. The read cycle is terminated by driving Chip Select ( $\overline{\text{CS}}$ ) high (Figure 5-10).

#### 5.12 Lock ID

The Lock ID instruction permanently locks the Identification Page in read-only mode. Before this instruction can be accepted, a Write Enable (WREN) instruction must have been executed. The Lock ID instruction is issued by driving Chip Select  $(\overline{CS})$  low, sending the instruction code, the address and a data byte on Serial Data input (SI), and driving Chip Select  $(\overline{CS})$  high. In the address sent, A10

must be equal to 1, all other address bits are Don't Care. The data byte sent must be equal to the binary value xxxx xx1x, where x = Don't Care.

Chip Select  $(\overline{CS})$  must be driven high after the rising edge of Serial Clock (SCK) that latches in the eighth bit of the data byte, and before the next rising edge of Serial Clock (SCK). Otherwise, the Lock ID instruction is not executed. Driving Chip Select  $(\overline{CS})$  high at a byte boundary of the input data triggers the self-timed write cycle whose duration is  $T_{WR}$ . The instruction sequence is shown in Figure 5-11.

The instruction is not accepted, and so not executed, under the following conditions:

- If the Write Enable Latch (WEL) bit has not been set to
   1 (by previously executing a Write Enable instruction).
- If Status register bits (BP1,BP0) = (1,1).
- If a write cycle is already in progress.
- If the device has not been deselected, by Chip Select (CS) being driven high, at a byte boundary (after the eighth bit, b0, of the last data byte that was latched in).
- If the Identification page is locked by the Lock Status bit.

**Table 5.4: Write Protection** 

WPEN	WP	Hardware Write Protection	WEN	Inside Block	Outside Block	Status Register (WPEN, BP1, BP0)
0	Χ	Not Enabled	0	Read-only	Read-only	Read-only
0	Χ	Not Enabled	1	Read-only	Unprotected	Unprotected
1	0	Enabled	0	Read-only	Read-only	Read-only
1	0	Enabled	1	Read-only	Unprotected	Read-only
Х	1	Not Enabled	0	Read-only	Read-only	Read-only
Х	1	Not Enabled	1	Read-only	Unprotected	Unprotected

Note: X = Don't care bit.

Table 5.5: Address Kev

Name	GT25C128A	
An	A <sub>13</sub> -A <sub>0</sub>	
Don't Care Bits	A <sub>15</sub> -A <sub>14</sub>	



### 5.13. Diagrams

Figure 5-1. Synchronous Data Timing

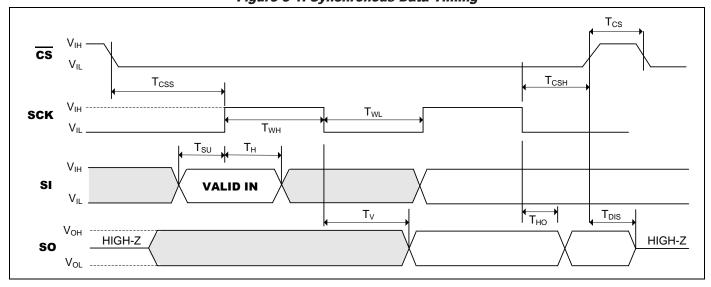


Figure 5-2. WREN Timing

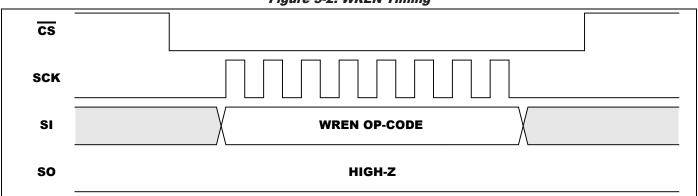
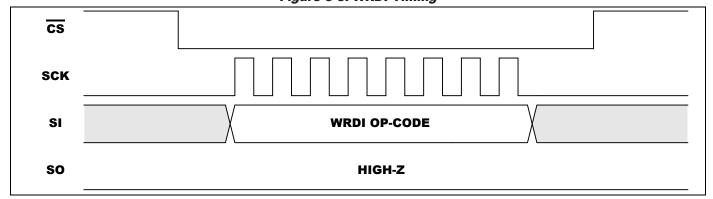
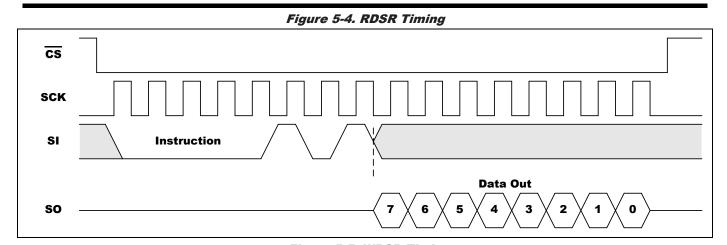
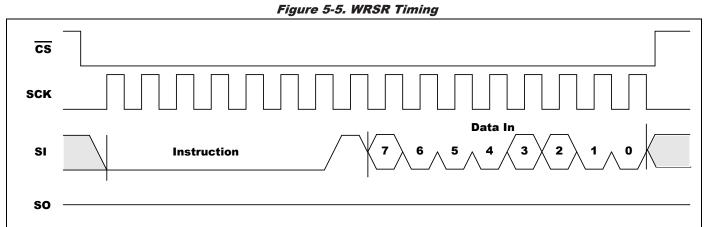


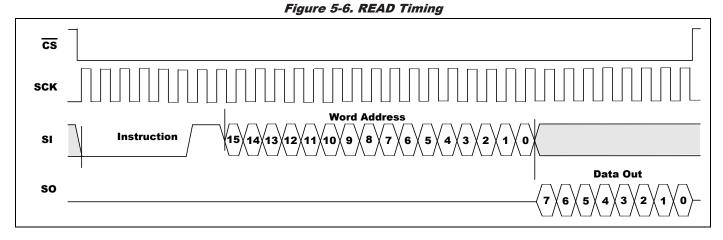
Figure 5-3. WRDI Timing





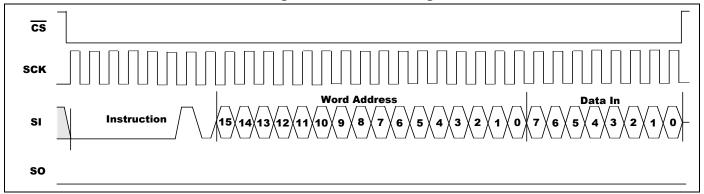




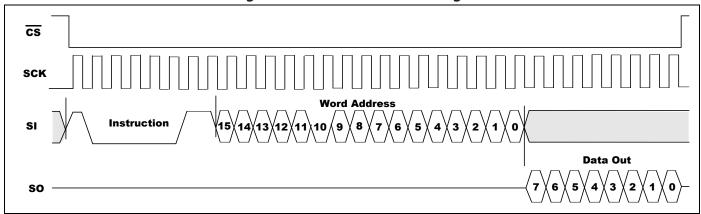








#### Figure 5-8. Read Identification Page



#### Figure 5-9. Write Identification Page

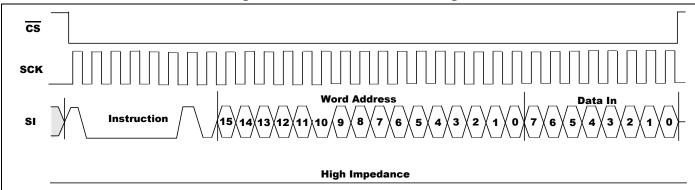




Figure 5-10. Read Lock Status

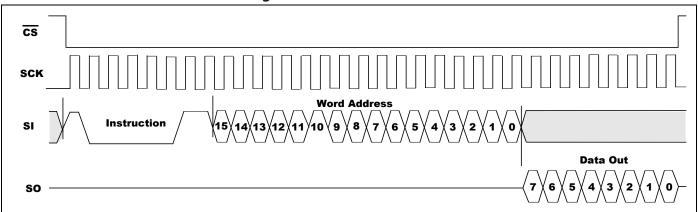


Figure 5-11. Lock ID

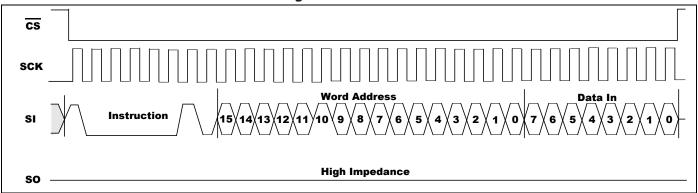
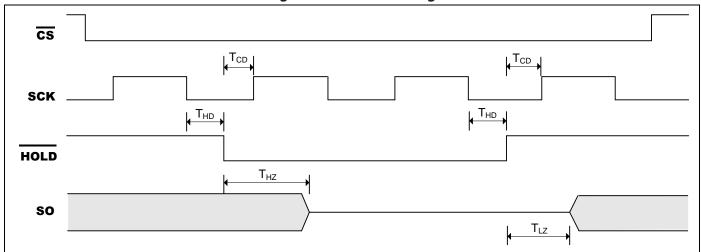


Figure 5-12. HOLD Timing







### 6. Electrical Characteristics

### **6.1 Absolute Maximum Ratings**

Symbol	Parameter	Value	Unit
Vs	Supply Voltage	-0.5 to V <sub>CC</sub> + 1	V
VP	Voltage on Any Pin	−0.5 to Vcc + 1	V
T <sub>BIAS</sub>	Temperature Under Bias	-55 to +125	°C
T <sub>STG</sub>	Storage Temperature	-65 to +150	°C
Іоит	Output Current	5	mA

Note: Stress greater than those listed under Absolute Maximum Ratings may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other condition outside those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

### **6.2 Operating Range**

Range	Ambient Temperature (T <sub>A</sub> )	Vcc
Automotive Grade 2	−40°C to +105°C	2.5V to 5.5V

#### 6.3 Reliability

Ambient Temperature (TA)	Symbol	Parameter	Min.	Unit
Ta=+25°C	End	Endurance	1 million	Program / Erase Cycles
	DR	Data Retention	100	Years

#### **6.4 Capacitance**

Symbol	Parameter <sup>[1, 2]</sup>	Conditions	Max.	Unit
C <sub>IN</sub>	Input Capacitance	$V_{IN} = 0V$	6	pF
C <sub>I/O</sub>	Input / Output Capacitance	$V_{I/O} = 0V$	8	pF

Notes: [1] Tested initially and after any design or process changes that may affect these parameters and not 100% tested.

<sup>&</sup>lt;sup>[2]</sup> Test conditions:  $T_A = 25^{\circ}C$ , f = 1 MHz,  $V_{CC} = 5.0V$ 



### **6.5 DC Electrical Characteristic**

Automotive:  $T_A = -40$ °C to +105°C,  $V_{cc} = 2.5V \sim 5.5V$ 

Symbol	bol Parameter		Vcc Test Conditions		Max.	Unit
Vcc	Supply Voltage			2.5	5.5	V
V <sub>IH</sub>	Input High Voltage			0.7* V <sub>CC</sub>	V <sub>CC</sub> +0.5	V
VIL	Input Low Voltage			-0.3	0.3* Vcc	V
ILI	Input Leakage Current		V <sub>IN</sub> = 0V To V <sub>CC</sub>	-2	2	μΑ
I <sub>LO</sub>	Output Leakage Current		Vout = 0V To Vcc, $\overline{\text{CS}}$ = Vcc	-2	2	μA
Vон	Output High Voltage	2.5	Iон = -0.4mA	0.8*Vcc	_	V
		5.5	I <sub>OH</sub> = -2 mA	0.8*Vcc	_	V
VoL	Output Low Voltage	2.5	I <sub>OL</sub> = 1.5 mA	_	0.4	V
		5.5	I <sub>OL</sub> = 2 mA	_	0.4	V
I <sub>CC1</sub>	Write Operating Current	2.5	Write at 10 MHz, SO=Open	_	3	mA
		5.5	Write at 20 MHz, SO=Open	_	4	mA
I <sub>CC2</sub>	Read Operating Current	2.5	Read at 10 MHz, SO=Open	_	3	mA
		5.5	Read at 20 MHz, SO=Open	_	5	mA
I <sub>SB</sub>	Standby Current	2.5	$V_{IN}=V_{CC}$ or GND, $\overline{CS}=V_{CC}$	_	15	μΑ
		5.5	$V_{IN} = V_{CC}$ or GND, $\overline{CS} = V_{CC}$	_	15	μΑ



#### **6.6 AC Electrical Characteristic**

Automotive:  $T_A = -40$ °C to +105°C, Supply voltage = 2.5V to 5.5V

	Parameter <sup>[1]</sup>	2.5V≤\	2.5V≤Vcc<4.5V		4.5V≤Vcc≤5.5V	
Symbol		Min.	Max.	Min.	Max.	Unit
F <sub>SCK</sub>	SCK Clock Frequency	0	10	0	20	MHz
$T_{RI}$	Input Rise Time	_	1	_	1	μs
T <sub>FI</sub>	Input Fall Time	_	1	_	1	μs
T <sub>WH</sub>	SCK High Time	40	_	20	_	ns
TwL	SCK Low Time	40	_	20	_	ns
Tcs	CS High Time	50	_	25	_	ns
T <sub>CSS</sub>	CS Setup Time	50	_	25	_	ns
Тсѕн	CS Hold Time	50	_	25	_	ns
T <sub>SU</sub>	Data In Setup Time	10	_	5	_	ns
Тн	Data In Hold Time	10	_	5	_	ns
T <sub>HD</sub>	HOLD Setup Time	10	_	5	_	ns
T <sub>CD</sub>	HOLD Hold Time	10	_	5	_	ns
T <sub>V</sub> <sup>[2]</sup>	Output Valid	0	40	0	20	ns
Тно	Output Hold Time	0	_	0	_	ns
T <sub>LZ</sub>	HOLD to Output Low Z	0	40	0	25	ns
T <sub>HZ</sub>	HOLD to Output High Z	_	40	_	40	ns
T <sub>DIS</sub>	Output Disable Time		40		40	ns
Twc	Write Cycle Time		5		5	ms

Notes: [1] The parameters are characterized but not 100% tested.

 $<sup>^{[2]}</sup>$ C<sub>L</sub> = 30pF (typical)



## 7. Ordering Information

Automotive Grade: -40°C to +105°C, Lead-free

Voltage Range	Part Number*	Package (8-pin)*
	GT25C128A-3GLA2-TR	150-mil SOIC
2.5V to 5.5V	GT25C128A-3ZLA2-TR	3 x 4.4 mm TSSOP
	GT25C128A-3UDLA2-TR	2 x 3 x 0.55 mm UDFN

1. Contact Giantec Sales Representatives for availability and other package information.

- 2. The product is packed in tape and reel "-TR" (4K per reel), except UDFN is 5K per reel.
- 3. Refer to Giantec website for related declaration document on lead free, RoHS, halogen free or Green, whichever is applicable.



### 8. Top Markings

#### 8.1 SOIC Package



G: Giantec Logo

5128A3GX: GT25C128A-3GLA2-TR YWW: Date Code, Y=year, WW=week

#### 8.2 TSSOP Package



GT: Giantec Logo

5128A3ZX: GT25C128A-3ZLA2-TR YWW: Date Code, Y=year, WW=week

### 8.3 UDFN Package



GT: Giantec Logo

57A2: GT25C128A-3UDLA2-TR

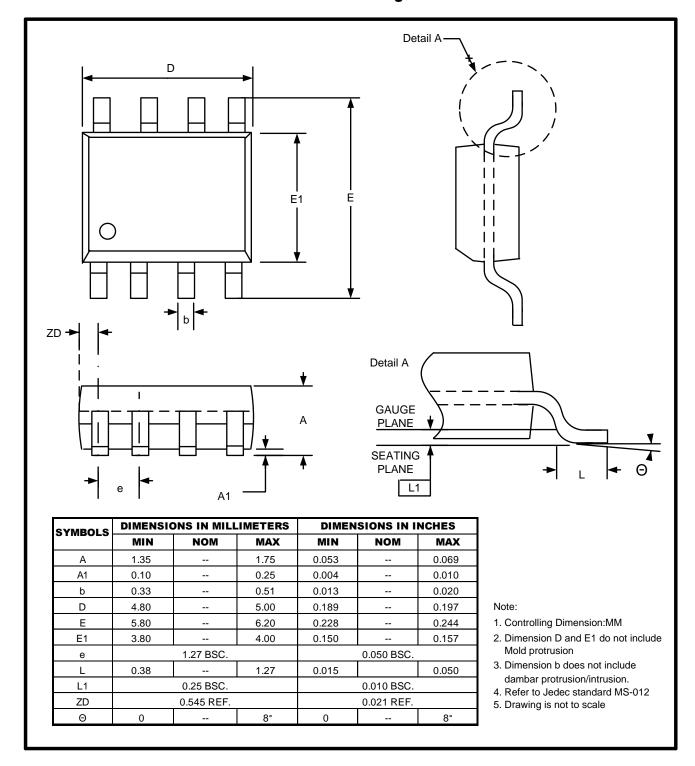
YWW: Date Code, Y=year, WW=week



### 9. Package Information

#### **9.1 SOIC**

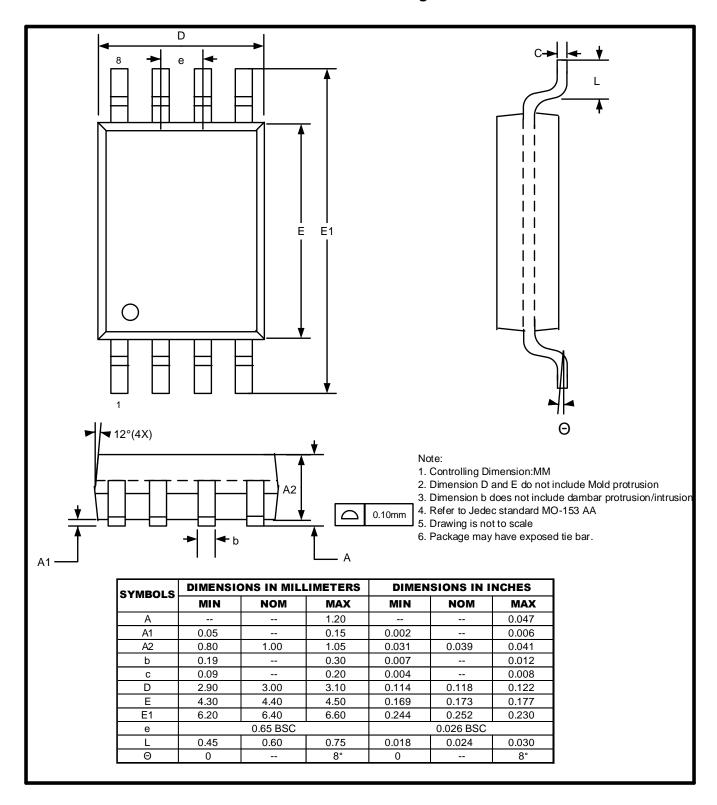
### **8L 150mil SOIC Package Outline**





#### **9.2 TSSOP**

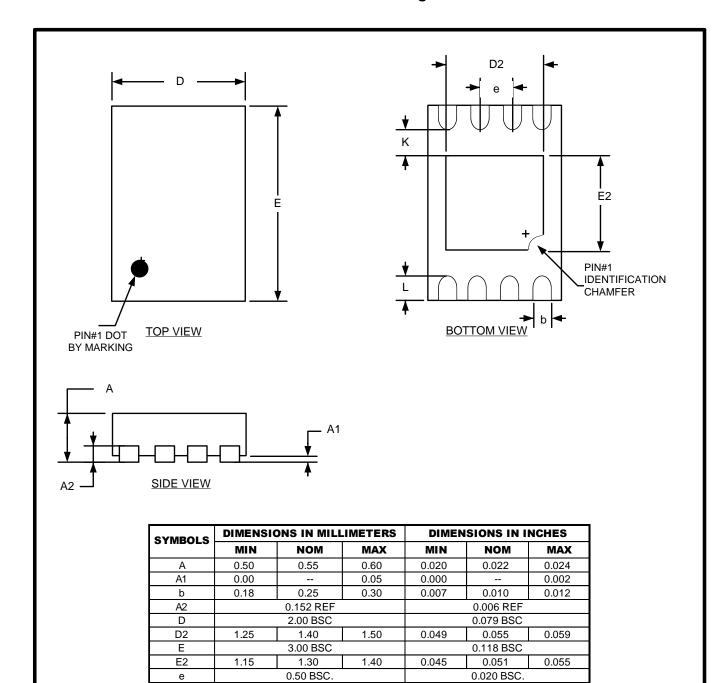
#### **8L 3x4.4mm TSSOP Package Outline**





#### **9.3 UDFN**

#### **8L 2x3mm UDFN Package Outline**



0.016

0.008

0.012

#### Note:

Κ

L

1. Controlling Dimension:MM

0.40

0.20

0.30

0.40

2. Drawing is not to scale

0.016



## **10. Revision History**

Revision	Date	Descriptions	
A0	Nov. 2015	Initial version	
A1	May. 2022	Update Logo and other	
A2	Feb. 2023	Add note for HOLD in 4.4	
A3	Mar. 2023	Update I <sub>cc1</sub> ,I <sub>SB</sub>	
A4	Dec. 2023	Update IsB	
A5	Aug.2024	Add some notes in Table 5.1	